

SEMICONDUCTOR WAFER GRINDING METHOD

ABSTRACT



To reduce the wafer production cost by grinding a sliced semiconductor wafer at a high accuracy and a high efficiency and supplying the wafer to the next polishing step. A semiconductor wafer is rough ground between grindstones by a fixed grindstone. After rough grinding, finish grinding by free abrasive grains is performed on the same grinding axis by supplying a slurry which suspends fine abrasive grain between the grindstones through slurry pipes. To perform finish grinding by free abrasive grains, a rotational speed and a feed rate of the grindstones are lowered to lower the grinding action by a fixed grindstone.